

UNCONTROLLED DOCUMENT

PART NUMBER		REV.
SML-LX0606SISYC-TR		C

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #11148	11.02.06
B	E.C.N. #11508.	03.05.09
C	E.C.N. #11581.	08.12.09

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^{\circ}\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		636 (RED)		nm	
		590 (YELLOW)		nm	
FORWARD VOLTAGE (R/Y)		2.0	2.6/2.5	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_r=100\mu\text{A}$
AXIAL INTENSITY (R/Y)		150/100		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		120		2x theta	
EMITTED COLOR:	RED/YELLOW				
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	COLORS	MAX	UNITS
PEAK FORWARD CURRENT*		160	mA
STEADY CURRENT		30	mA
POWER DISSIPATION		100	mW
DERATE FROM 25°C		-1.2	mW/°C
OPERATING TEMP.		-40 TO +85	°C
STORAGE TEMP.		-40 TO +85	°C

* $t < 10\mu\text{s}$

NOTES:

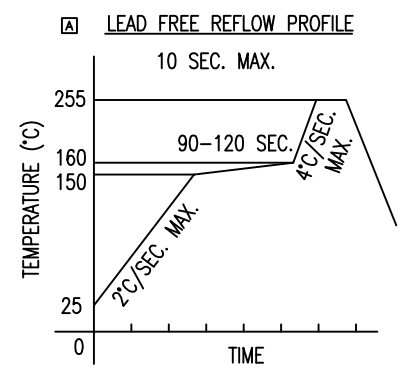
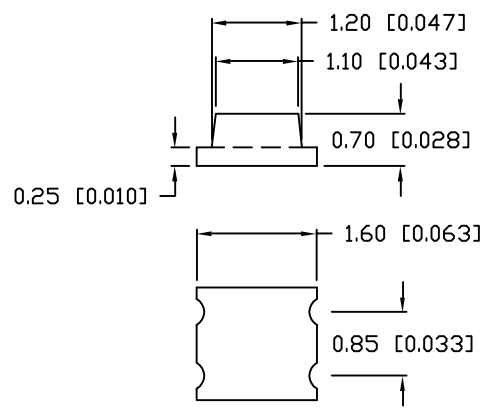
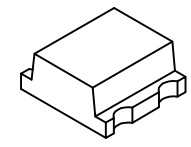
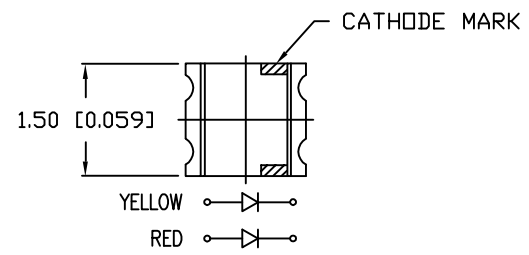
- THE CATHODE MARK IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.

CAUTION: MOISTURE SENSITIVE DEVICE
PER JEDEC LEVEL 3 STANDARDS

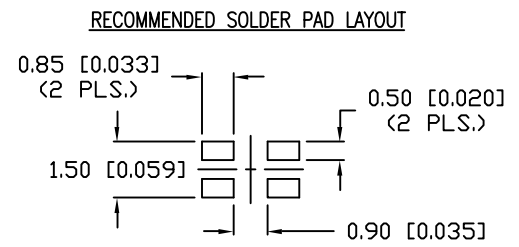
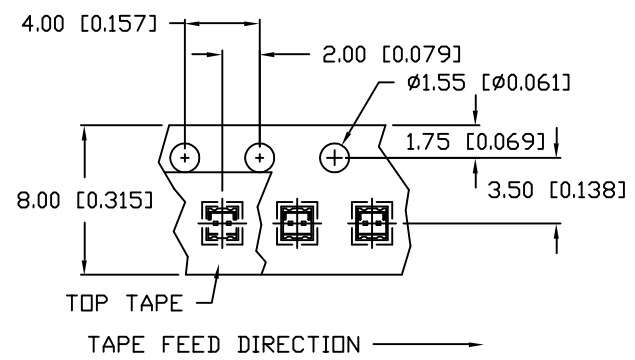


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*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (0.002), LEAD LENGTH=±0.75 (±0.030). MIN.= +DECIMAL PRECISION MAX.= +0.00 -DECIMAL PRECISION



TOTAL TIME ABOVE 220°C IS 60 SECONDS MAX.



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1.6mm x 1.5mm ULTRA THIN SURFACE MOUNT LED,
636nm AlInGaP RED/590nm AlInGaP YELLOW BICOLOR LED,
WATER CLEAR LENS, TAPE AND REEL.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY:	CHECKED BY:	APPROVED BY:	DATE: 11.02.06
JC			PAGE: 1 OF 1
			SCALE: N/A